

# 100V N-Ch Power MOSFET

## Feature

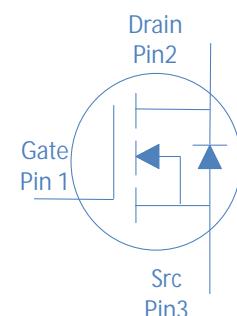
High Speed Power Switching  
 Enhanced Body diode dv/dt capability  
 Enhanced Avalanche Ruggedness  
 100% UIS Tested, 100% Rg Tested  
 Lead Free

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## Application

Synchronous Rectification in SMPS  
 Hard Switching and High Speed Circuit  
 Power Tools  
 UPS  
 Motor Control

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|--|--|--|
|  |  |  |
|  |  |  |
|  |  |  |



|  | Conditions |  |
|--|------------|--|
| Continuous Drain Current (Silicon Limited) | c          |  |
| Continuous Drain Current (Package Limited) | c          |  |
| Pulsed Drain Current                       | c          |  |
|  | c          |  |
|  | c          |  |

| Thermal Resistance Junction-Case | JC |  |
|----------------------------------|----|--|
|                                  | JA |  |



Fall Time

**Reverse Diode Characterim harge**

Diode Forward Voltage

Reverse Recovery Charge

F

F

nC

Fig 1. Typical Output Characteristics

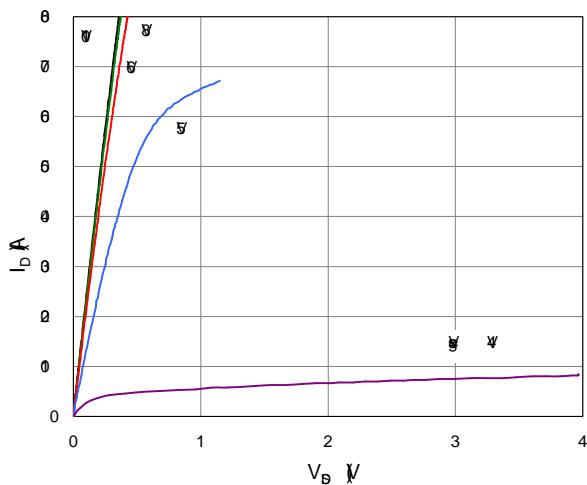


Figure 2. On-Resistance vs. Gate-Source Voltage

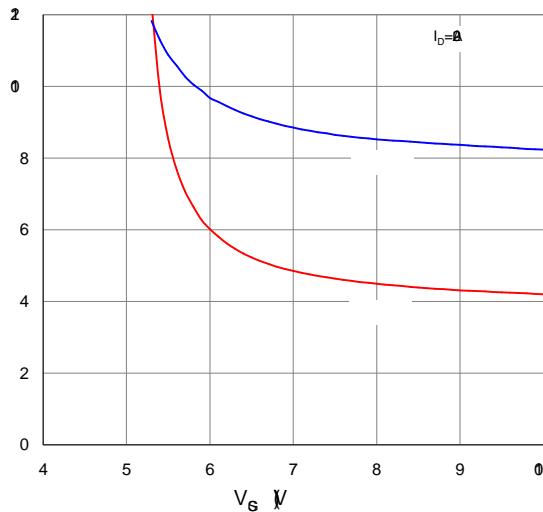


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

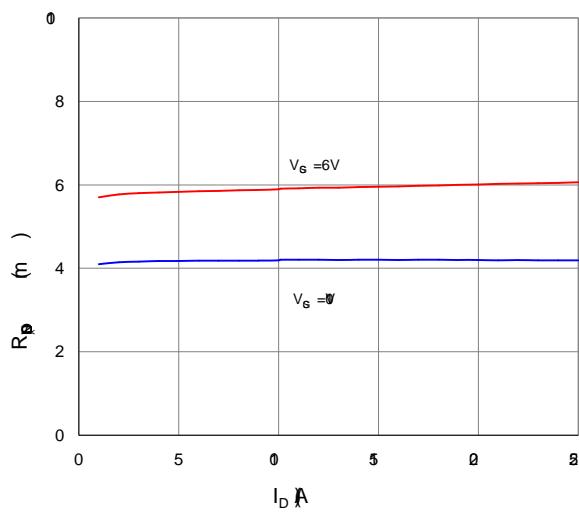


Figure 4. Normalized On-Resistance vs. Junction Temperature

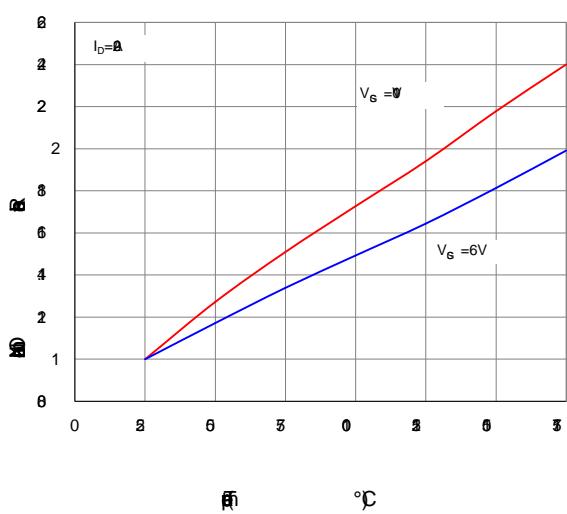


Figure 5. Typical Transfer Characteristics

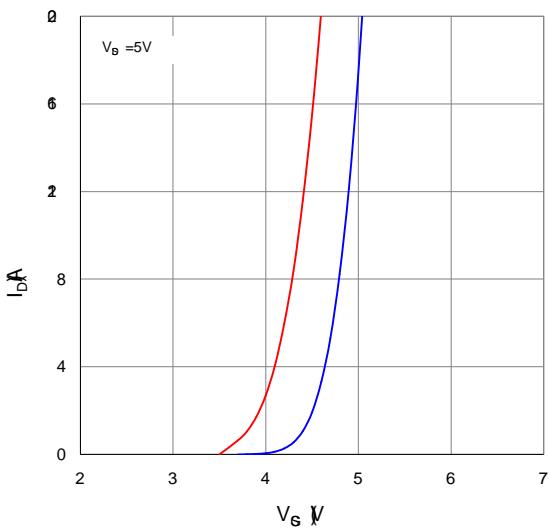


Figure 6. Typical Source-Drain Diode Forward Voltage

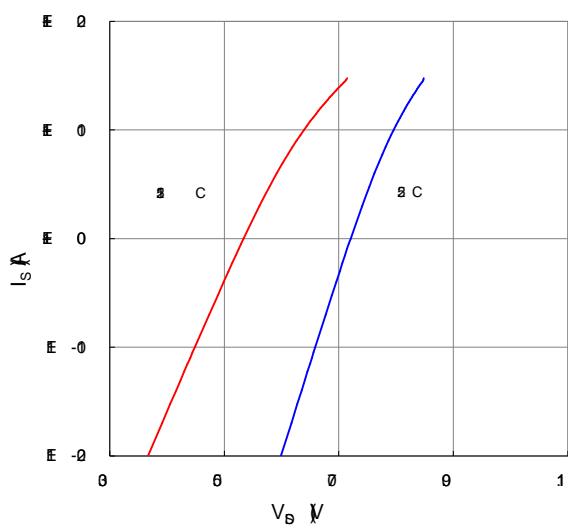


Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage

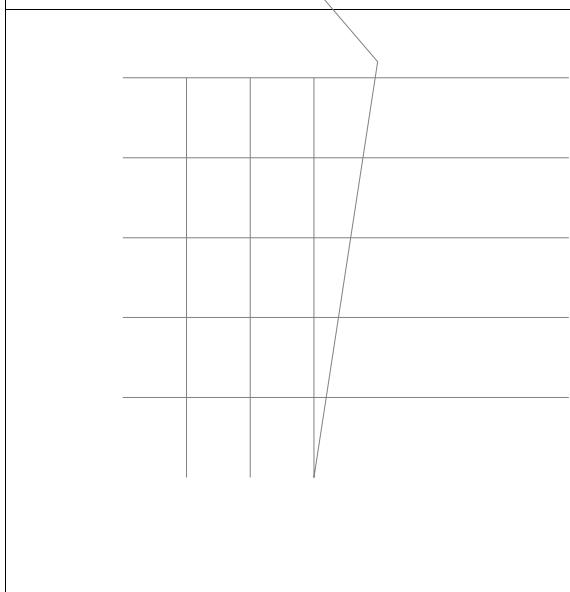


Figure 8. Typical Capacitance vs. Drain-to-Source Voltage

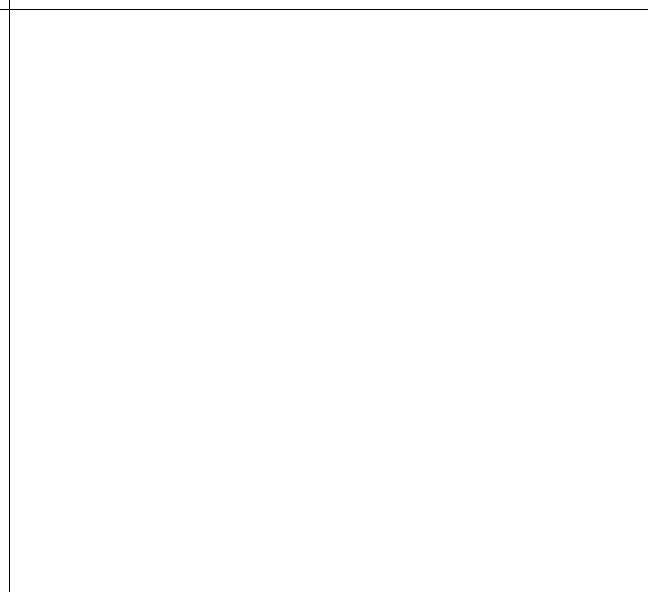


Figure 9. Maximum Safe Operating Area

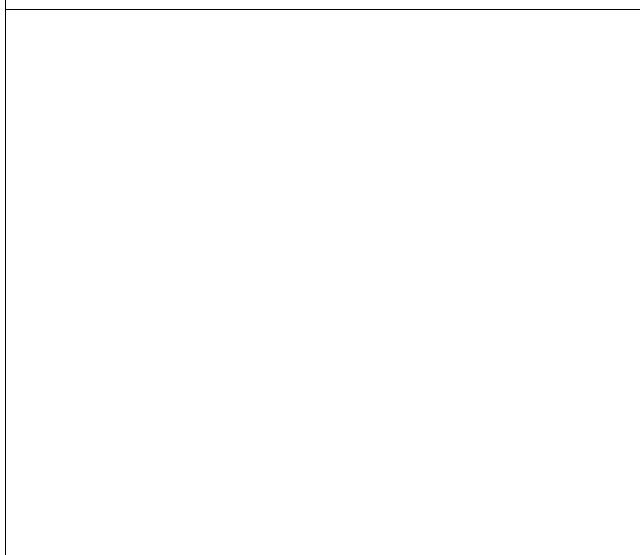


Figure 10. Maximum Drain Current vs. Case Temperature

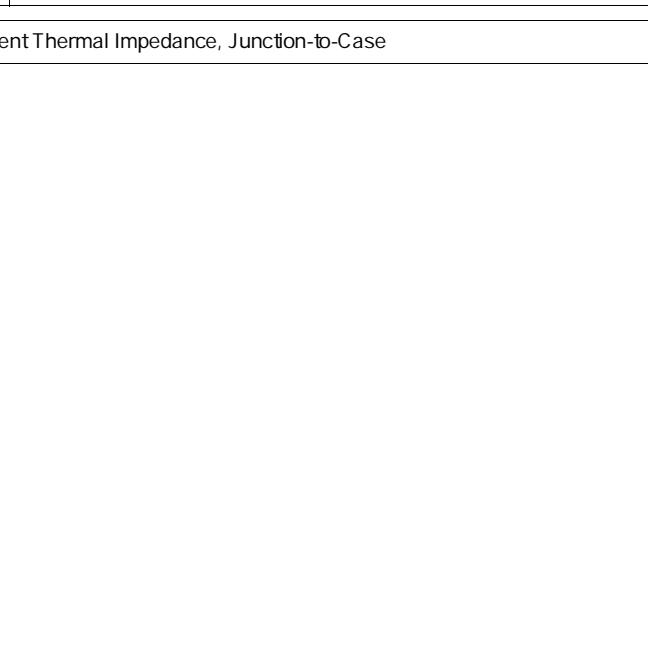
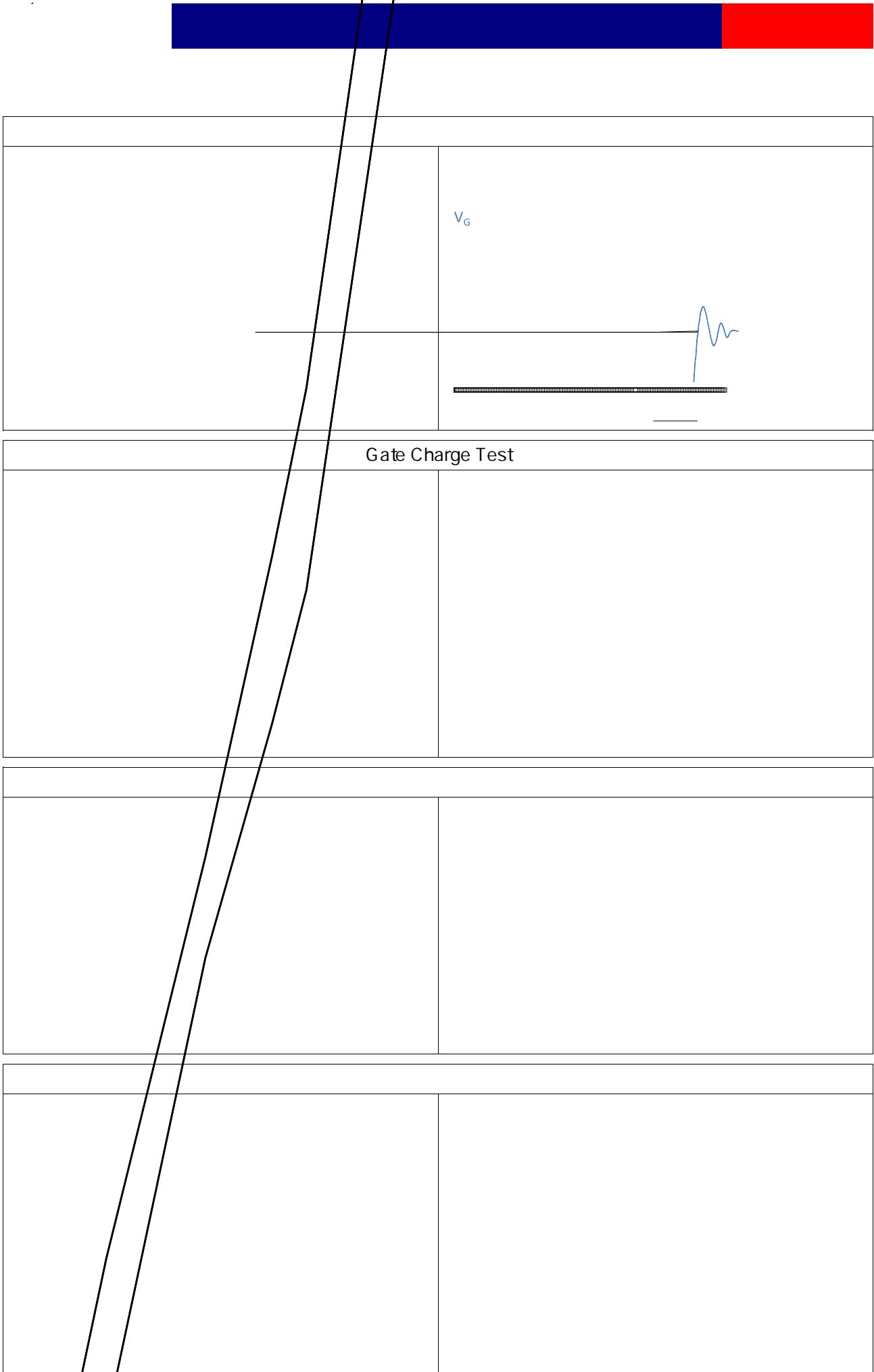


Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Case





10.28

15.80

C

13.48

0.82

2.80

6.80

10.28

C

8.59

0.83

5.08

F

1.28